

Is Now Part of



ON Semiconductor®

To learn more about ON Semiconductor, please visit our website at www.onsemi.com

Please note: As part of the Fairchild Semiconductor integration, some of the Fairchild orderable part numbers will need to change in order to meet ON Semiconductor's system requirements. Since the ON Semiconductor product management systems do not have the ability to manage part nomenclature that utilizes an underscore (_), the underscore (_) in the Fairchild part numbers will be changed to a dash (-). This document may contain device numbers with an underscore (_). Please check the ON Semiconductor website to verify the updated device numbers. The most current and up-to-date ordering information can be found at www.onsemi.com. Please email any questions regarding the system integration to Fairchild guestions@onsemi.com.

ON Semiconductor and the ON Semiconductor logo are trademarks of Semiconductor Components Industries, LLC dba ON Semiconductor or its subsidiaries in the United States and/or other countries. ON Semiconductor owns the rights to a number of patents, trademarks, copyrights, trade secrets, and other intellectual property. A listing of ON Semiconductor's product/patent coverage may be accessed at www.onsemi.com/site/pdf/Patent-Marking.pdf. ON Semiconductor reserves the right to make changes without further notice to any products herein. ON Semiconductor makes no warranty, representation or guarantee regarding the suitability of its products for any particular purpose, nor does ON Semiconductor assume any liability arising out of the application or use of any product or circuit, and specifically disclaims any and all liability, including without limitation special, consequential or incidental damages. Buyer is responsible for its products and applications using ON Semiconductor products, including compliance with all laws, regulations and safety requirements or standards, regardless of any support or applications information provided by ON Semiconductor. "Typical" parameters which may be provided in ON Semiconductor data sheets and/or specifications can and do vary in different applications and actual performance may vary over time. All operating parameters, including "Typicals" must be validated for each customer application by customer's technical experts. ON Semiconductor does not convey any license under its patent rights nor the rights of others. ON Semiconductor products are not designed, intended, or authorized for use as a critical component in life support systems or any EDA Class 3 medical devices or medical devices with a same or similar classification in a foreign jurisdiction or any devices intended for implantation in the human body. Should Buyer purchase or use ON Semiconductor products for any such unintended or unauthorized application, Buyer shall indemnify and hold ON Semiconductor and its officer



April 2015

FDB082N15A

N-Channel PowerTrench[®] MOSFET 150 V, 117 A, 8.2 m Ω

Features

- $R_{DS(on)}$ = 6.7 m Ω (Typ.) @ V_{GS} = 10 V, I_D = 75 A
- · Fast Switching Speed
- Low Gate Charge, Q_G = 64.5 nC (Typ.)
- High Performance Trench Technology for Extremely Low $R_{DS(on)}$
- · High Power and Current Handling Capability
- RoHS Compliant

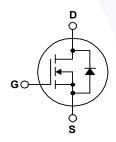
Description

This N-Channel MOSFET is produced using Fairchild Semiconductor's advance PowerTrench® process that has been tailored to minimize the on-state resistance while maintaining superior switching performance.

Applications

- · Synchronous Rectification for ATX / Server / Telecom PSU
- · Battery Protection Circuit
- · Motor drives and Uninterruptible Power Supplies
- Micro Solar Inverter





Absolute Maximum Ratings T_C = 25°C unless otherwise noted.

Symbol		Parameter	FDB082N15A	Unit	
V _{DSS}	Drain to Source Voltage		150	V	
V	Cata ta Sauraa Valtaga	- DC	±20	V	
V_{GSS}	Gate to Source Voltage	- AC (f > 1 Hz)	±30	V	
I _D	Drain Current	- Continuous (T _C = 25°C, Silicon Limited)	117	^	
	Drain Current	- Continuous (T _C = 100°C, Silicon Limited)	83	— A	
I _{DM}	Drain Current	- Pulsed (Note 1)	468	Α	
E _{AS}	Single Pulsed Avalanche Energ	gy (Note 2)	542	mJ	
dv/dt	Peak Diode Recovery dv/dt	(Note 3)	6	V/ns	
D	Device Discipation	$(T_C = 25^{\circ}C)$	294	W	
P_{D}	Power Dissipation	- Derate Sbove 25°C	1.96	W/°C	
T _J , T _{STG}	Operating and Storage Temper	ature Range	-55 to +175	°C	
Tı	Maximum Lead Temperature for	or Soldering, 1/8" from Case for 5 Seconds	300	οС	

Thermal Characteristics

Symbol	Parameter	FDB082N15A	Unit
$R_{\theta JC}$	Thermal Resistance, Junction to Case, Max.	0.51	°C/W
$R_{\theta JA}$	Thermal Resistance, Junction to Ambient, Max.	62.5	-C/VV

Package Marking and Ordering Information

Part Number	Top Mark	Package	Packing Method	Reel Size	Tape Width	Quantity
FDB082N15A	FDB082N15A	D ² -PAK	Tape and Reel	330 mm	24 mm	800 units

Electrical Characteristics $T_C = 25^{\circ}C$ unless otherwise noted.

Symbol	Parameter	Test Conditions	Min.	Тур.	Max.	Unit
Off Charac	cteristics					
BV _{DSS}	Drain to Source Breakdown Voltage	$I_D = 250 \mu A, V_{GS} = 0 V, T_C = 25^{\circ}C$	150	-	-	V
ΔBV _{DSS} / ΔΤ _J	Breakdown Voltage Temperature Coefficient	I_D = 250 μ A, Referenced to 25°C	-	0.08	-	V/°C
ı	Zero Gate Voltage Drain Current	V _{DS} = 120 V, V _{GS} = 0 V	-	-	1	
IDSS	Zero Gate voltage Drain Current	$V_{DS} = 120 \text{ V}, T_{C} = 150^{\circ}\text{C}$	-	-	500	μА
I _{GSS}	Gate to Body Leakage Current	V _{GS} = ±20 V, V _{DS} = 0 V	-	-	±100	nA

On Characteristics

V _{GS(th)}	Gate Threshold Voltage	$V_{GS} = V_{DS}, I_{D} = 250 \mu A$	2.0	-	4.0	V
R _{DS(on)}	Static Drain to Source On Resistance	V _{GS} = 10 V, I _D = 75 A	-	6.7	8.20	mΩ
9 _{FS}	Forward Transconductance	V _{DS} = 10 V, I _D = 75 A	-	139	-	S

Dynamic Characteristics

-						
C _{iss}	Input Capacitance	V - 25 V V - 0 V	\ -	4645	6040	pF
C _{oss}	Output Capacitance	V _{DS} = 25 V, V _{GS} = 0 V, f = 1 MHz	-	1445	1880	pF
C _{rss}	Reverse Transfer Capacitance	1 - 1 101112	-\	100	-	pF
C _{iss}	Input Capacitance	V - 75 V V - 0 V	-	4570	6040	pF
C _{oss}	Output Capacitance	V _{DS} = 75 V, V _{GS} = 0 V, f = 1 MHz	-	460	1880	pF
C _{rss}	Reverse Transfer Capacitance	1 - 1 101112	-	20	-	pF
Q _{g(tot)}	Total Gate Charge at 10V		-	64.5	84	nC
Q _{gs}	Gate to Source Gate Charge	$V_{DS} = 120 \text{ V}, I_{D} = 75 \text{ A},$	-	19.1	-	nC
Q _{gs2}	Gate Charge Threshold to Plateau	V _{GS} = 10 V	-	8.7	-	nC
Q_{gd}	Gate to Drain "Miller" Charge	(Note4	-	13.5	-	nC
ESR	Equivalent Series Resistance (G-S)	f = 1 MHz	- /	2.5	-	Ω

Switching Characteristics

t _{d(on)}	Turn-On Delay Time	V _{DD} = 75 V, I _D = 75 A,	-	22	54	ns
t _r	Turn-On Rise Time	$V_{GS} = 10 \text{ V}, R_{G} = 4.7 \Omega$	/ -	58	126	ns
t _{d(off)}	Turn-Off Delay Time		-	61	132	ns
t _f	Turn-Off Fall Time	(Note4)	-	26	62	ns

Drain-Source Diode Characteristics

I _S	Maximum Continuous Drain to Source Diode Forward Current			-	117	Α
I _{SM}	Maximum Pulsed Drain to Source Diode Forward Current			-	468	Α
V_{SD}	Drain to Source Diode Forward Voltage V _{GS} = 0 V, I _{SD} = 75 A		-	-	1.25	V
t _{rr}	Reverse Recovery Time	V _{GS} = 0 V, I _{SD} = 75 A,	-	96	// -	ns
Q _{rr}	Reverse Recovery Charge	$dI_F/dt = 100 A/\mu s$	-	268	\\ - \\	nC

Notes

- 1. Repetitive rating: pulse-width limited by maximum junction temperature.
- 2. Starting T_J = 25°C, L = 3 mH, I_{SD} = 19 A.
- 3. I $_{SD} \leq 75$ A, di/dt ≤ 200 A/µs, V $_{DD} \leq BV_{DSS},$ starting T $_{J}$ = 25°C.
- 4. Essentially independent of operating temperature typical characteristics.

Typical Performance Characteristics

Figure 1. On-Region Characteristics

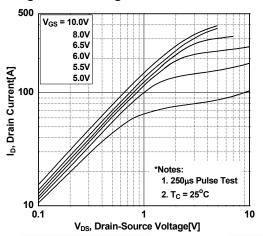


Figure 3. On-Resistance Variation vs.

Drain Current and Gate Voltage

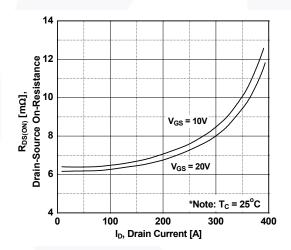


Figure 5. Capacitance Characteristics

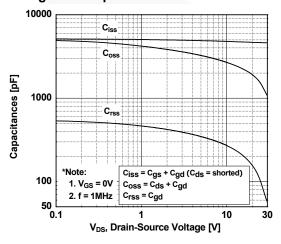


Figure 2. Transfer Characteristics

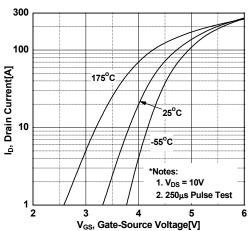


Figure 4. Body Diode Forward Voltage Variation vs. Source Current and Temperature

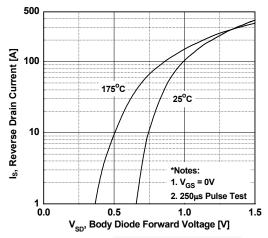
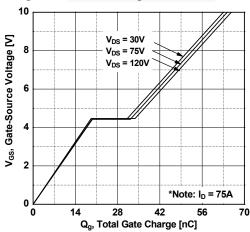


Figure 6. Gate Charge Characteristics



Typical Performance Characteristics (Continued)

Figure 7. Breakdown Voltage Variation vs. Temperature

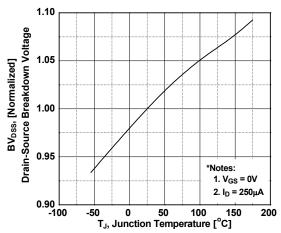


Figure 9. Maximum Safe Operating Area

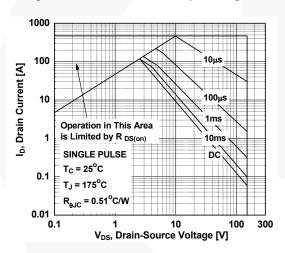


Figure 11. Unclamped Inductive Switching Capability

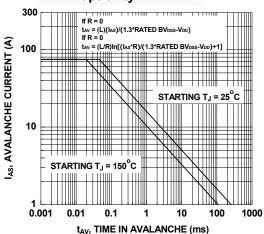


Figure 8. On-Resistance Variation vs. Temperature

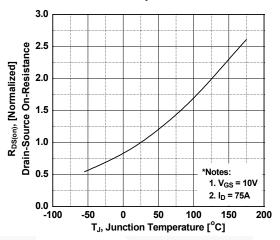
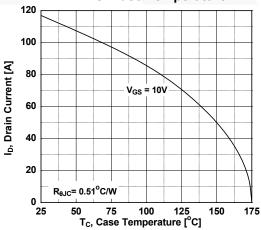
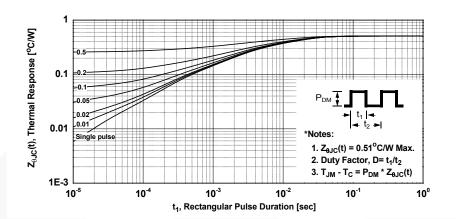


Figure 10. Maximum Drain Current vs. Case Temperature



Typical Performance Characteristics

Figure 12. Transient Thermal Response Curve



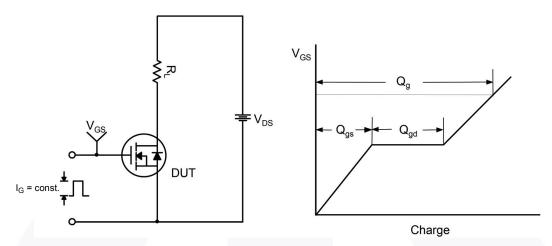


Figure 13. Gate Charge Test Circuit & Waveform

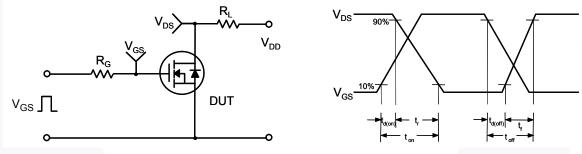


Figure 14. Resistive Switching Test Circuit & Waveforms

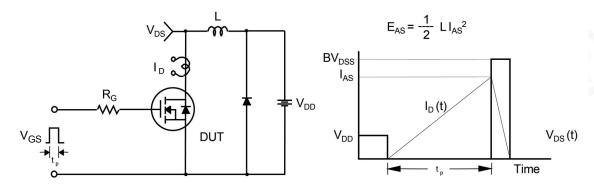


Figure 15. Unclamped Inductive Switching Test Circuit & Waveforms

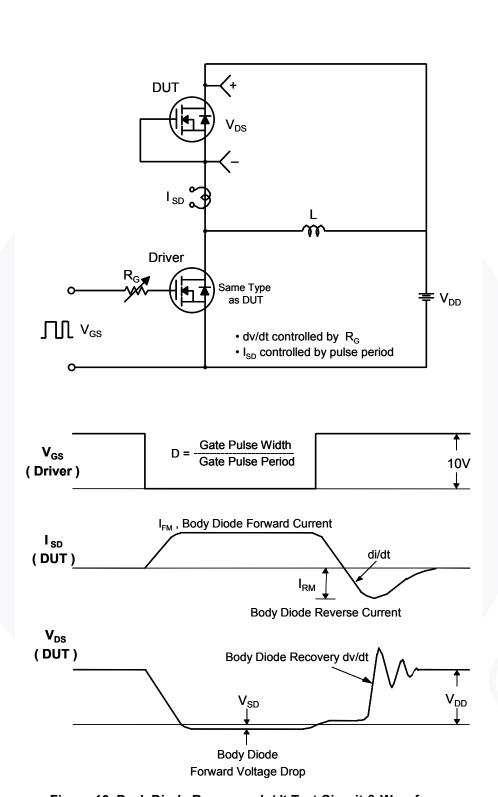
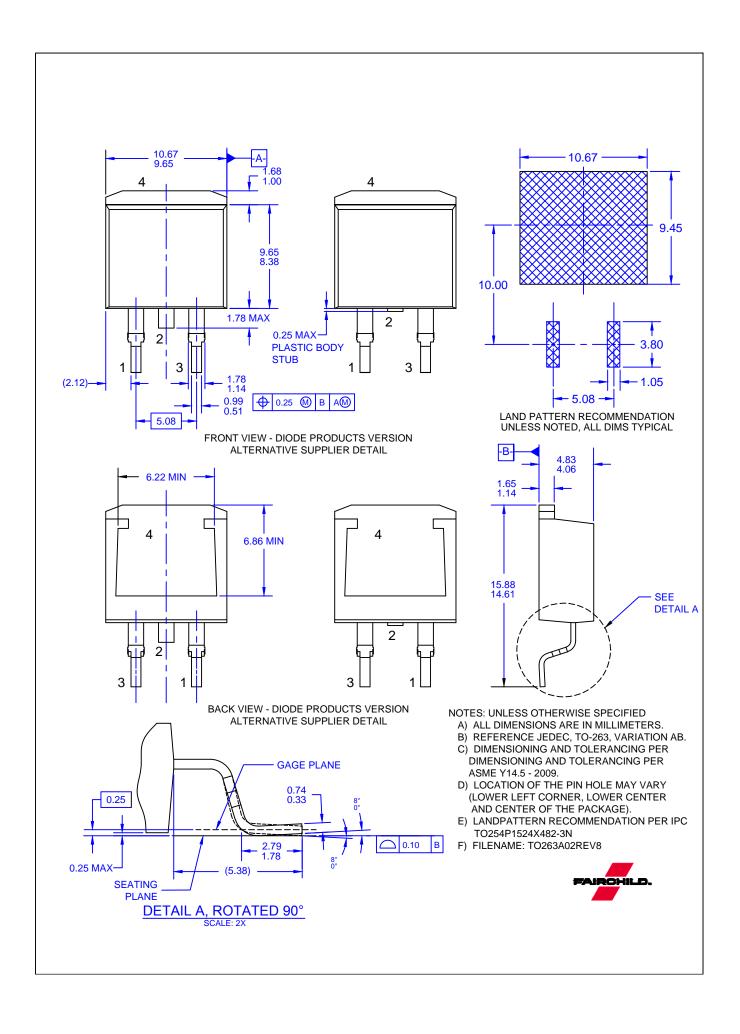


Figure 16. Peak Diode Recovery dv/dt Test Circuit & Waveforms



ON Semiconductor and in are trademarks of Semiconductor Components Industries, LLC dba ON Semiconductor or its subsidiaries in the United States and/or other countries. ON Semiconductor owns the rights to a number of patents, trademarks, copyrights, trade secrets, and other intellectual property. A listing of ON Semiconductor's product/patent coverage may be accessed at www.onsemi.com/site/pdt/Patent-Marking.pdf. ON Semiconductor reserves the right to make changes without further notice to any products herein. ON Semiconductor assume any liability arising out of the application or use of any product or circuit, and specifically disclaims any and all liability, including without limitation special, consequential or incidental damages. Buyer is responsible for its products and applications using ON Semiconductor products, including compliance with all laws, regulations and safety requirements or standards, regardless of any support or applications information provided by ON Semiconductor. "Typical" parameters which may be provided in ON Semiconductor data sheets and/or specifications can and do vary in different applications and actual performance may vary over time. All operating parameters, including "Typicals" must be validated for each customer application by customer's technical experts. ON Semiconductor does not convey any license under its patent rights nor the rights of others. ON Semiconductor products are not designed, intended, or authorized for use as a critical component in life support systems or any FDA Class 3 medical devices or medical devices with a same or similar classification in a foreign jurisdiction or any devices intended for implantation in the human body. Should Buyer purchase or use ON Semiconductor products for any such unintended or unauthorized application, Buyer shall indemnify and hold ON Semiconductor and its officers, employees, subsidiaries, affiliates, and distributors harmless against all claims, costs, damages, and exp

PUBLICATION ORDERING INFORMATION

LITERATURE FULFILLMENT:

Literature Distribution Center for ON Semiconductor 19521 E. 32nd Pkwy, Aurora, Colorado 80011 USA Phone: 303-675-2175 or 800-344-3860 Toll Free USA/Canada Fax: 303-675-2176 or 800-344-3867 Toll Free USA/Canada Email: orderlit@onsemi.com N. American Technical Support: 800-282-9855 Toll Free USA/Canada
Europe, Middle East and Africa Technical Support:
Phone: 421 33 790 2910
Japan Customer Focus Center
Phone: 81-3-5817-1050

ON Semiconductor Website: www.onsemi.com

Order Literature: http://www.onsemi.com/orderlit

For additional information, please contact your local Sales Representative

Mouser Electronics

Authorized Distributor

Click to View Pricing, Inventory, Delivery & Lifecycle Information:

ON Semiconductor: FDB082N15A